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PATENT & TRADEMARK OFFICE
TESSERA 3.3-018 CONT CONT II DIVCONTII
Serial No.: Unassigned
United States Patent No. 5,679,977, was in turn a
continuation of United States Patent Application No.
07/765,928, filed September 24, 1991, now United States
Patent No. 5,347,159. Said United States Patent Application
No. 07/765,928 was a continuation in part of United States
Patent Application No. 07/673,020, filed March 21, 1991, now
United States Patent No. 5,148,265 and said United States
Patent Application No. 07/765,928 was a continuation in part
of United States Patent Application No. 07/586,758, filed
September 24, 1990, now United States Patent No. 5,148,266.
Said United States Patent Application No. 08/030,194 is also
a continuation in part of said United States Patent
Application Nos. 07/586,758 and 07/673,020.

Page 1, line 9, delete "TECHNICAL FIELD" and insert

-- BACKGROUND OF THE INVENTION --.

Page 6, line 9, change "sulder" to -- solder --.

Page 12, line 24, change "thermolcompression" to
-- thermocompression --.

Page 18, line 13, delete "." and insert therefore -
-;

Figs. 31, 32 and 33 are diagrammatic, perspective
views depicting further embodiments according to the
invention.--

Page 33, line 23, change "centerto-center" to --
center-to-center --.

IN THE ABSTRACT:

Please cancel the abstract presently on file and
substitute therefor the following: -- ABSTRACT OF THE
DISCLOSURE

A semiconductor chip assembly, comprises a first
semiconductor chip having a front surface, a rear surface and
contacts on the front surface and a second semiconductor chip
having a front surface, a rear surface and contacts on the